

**AMENDMENTS TO THE CLAIMS**

Please amend the claims as follows:

1. (Currently Amended) A leadframe comprising:  
a plurality of leads, each lead comprising a first surface, an opposite second surface, an inner end segment which defines an inner end of the lead, and an outer portion extending from the inner end segment,

wherein a first subset of the leads each include a recess in the first surface of the lead at the inner end segment, a second subset of the leads each include a recess in the second surface of the lead at the inner end segment, and the individual leads of the first subset are situated in an alternating lateral pattern with the individual leads of the second subset such that the recesses in the inner end segments of the leads of any pair of adjacent leads are oriented in opposite directions, **the inner end segments of the leads of the second subset each including a pedestal between the inner end of the lead and the recess.**

2. (Cancelled)

3. (Currently Amended) The leadframe of claim 1, wherein the recess of the inner end segment of **each of** the leads of the first subset ~~does not extend~~ **extends** to the inner end of the lead, and the leads of the ~~first~~ **second** subset extend further toward a center of the leadframe than the leads of the ~~second~~ **first** subset.

4. (Previously Presented) The leadframe of claim 1, wherein the inner end of each of the leads is of a first width, and at least a portion of the outer portion of each of the leads is of a second width which is less than the first width.

5. (Cancelled)

6. (Original) The leadframe of claim 1, wherein each recess has a vertical depth that is more than half of a vertical height of the lead.

7. (Previously Presented) The leadframe of claim 1, further comprising a plurality of electrical conductors, wherein the inner end segments are respectively electrically connected to a semiconductor chip by one of said plurality of electrical conductors.

8. (Previously Presented) The leadframe of claim 7, where at least some of the plurality of electrical conductors are respectively electrically connected within the recess of the respective inner end segment.

9. (Currently Amended) A leadframe comprising:  
a plurality of pairs of adjacent metal leads, wherein each lead includes **opposite first and second surfaces**, an inner end segment which defines an inner end of the lead and has a recessed surface, and an outer portion extending from the inner end segment, and

wherein the recessed surfaces of the leads of each said pair of adjacent leads are **oriented in opposite directions and** spaced apart a first distance in a vertical direction, and said first distance is greater than a second distance in a horizontal direction between closest portions of the recessed surfaces of the leads of each said pair of adjacent leads, **one lead of each said pair including a pedestal between the inner end of the lead and the recessed surface which projects downwardly away from the first surface thereof**.

10. (Original) The leadframe of claim 9, wherein the first distance is greater than half a vertical height of an unrecessed portion of the lead.

11. (Original) The leadframe of claim 9, wherein the second distance is approximately zero.

12. (Previously Presented) The leadframe of claim 11, wherein the second distance is zero.

13. (Cancelled)

14. (Previously Presented) The leadframe of claim 9, further comprising a plurality of electrical conductors, wherein the inner end segments of the leads are respectively electrically connected to a semiconductor chip by one of said plurality of electrical conductors, and at least some of said plurality of electrical conductors are connected to the recessed surface of the respective inner end segment.

15. (Cancelled)

16. (Previously Presented) The leadframe of claim 9, further comprising a dam bar connected to the outer segments of the leads.

17. (Currently Amended) A leadframe comprising:

a plurality of adjacent pairs of leads each including **opposite first and second surfaces**, an inner segment which defines an inner end of the lead and has a recessed surface, and an outer portion extending from the inner segment, the recessed surfaces of the inner end segments of the leads of each of the pairs being oppositely oriented, **with one lead of each said pair including a pedestal between the inner end of the lead and the recessed surface which projects downwardly away from the first surface thereof.**

18. (Cancelled)

19. (Previously Presented) The leadframe of claim 17, further comprising a plurality of electrical conductors, wherein the inner end segments of the pairs of adjacent leads are respectively electrically connected to a semiconductor chip by one of said plurality of electrical conductors, and at least some of said plurality of electrical conductors are connected to the recessed surface of the respective inner end segment.

20. (Cancelled)

21. (Cancelled)

22. (Previously Presented) The leadframe of claim 17, wherein the inner end segment of each of the leads is of a first width, and at least a portion of the outer portion of each of the leads is of a second width which is less than the first width.

23. (Currently Amended) A semiconductor package comprising:

a plurality of adjacent pairs of leads each including **opposite first and second surfaces**, an inner segment which defines an inner end of the lead and has a recessed surface, and an outer portion extending from the inner segment, the recessed surfaces of the inner end segments of the leads of each of the pairs being oppositely oriented, **with one lead of each said pair including a pedestal between the inner end of the lead and the recessed surface which projects downwardly away from the first surface thereof;**

a semiconductor chip in an electrical connection with the inner end segments of the leads; and

a hardened encapsulant material covering the semiconductor chip, and the inner end segments of the leads.

24. (Previously Presented) The semiconductor package of claim 23, wherein the electrical connection comprises a plurality of electrical connectors bonded between the semiconductor chip and the inner end segments, wherein at least some of said plurality of electrical conductors are bonded to the recessed surface of the respective inner end surface.

25. (Cancelled)

26. (Cancelled)

27. (Cancelled)

28. (Previously Presented) The semiconductor package of claim 23, wherein the inner end segment of each of the leads is of a first width, and at least a portion of the outer portion of each of the leads is of a second width which is less than the first width.

29. (Currently Amended) A semiconductor package comprising:

a plurality of pairs of adjacent metal leads, wherein each lead includes **opposite first and second surfaces**, an inner end segment which defines an inner end of the lead and has a recessed surface, and an outer portion extending from the inner end segment, and

wherein the recessed surfaces of the leads of each said pair of adjacent leads are **oriented in opposite directions and** spaced apart a first distance in a vertical direction, and said first distance is greater than a second distance in a horizontal direction between closest portions of the recessed surfaces of the leads of each said pair of adjacent leads, **with one lead of each said pair including a pedestal between the inner end of the lead and the recessed surface which projects downwardly away from the first surface thereof;**

a semiconductor chip in an electrical connection with the inner end segments of the leads; and

a hardened encapsulant material covering the semiconductor chip, the conductors, and the inner end segments of the leads.

30. (Original) The semiconductor package of claim 29, wherein the first distance is greater than half a vertical height of an unrecessed portion of the lead.

31. (Original) The semiconductor package of claim 29, wherein the second distance is approximately zero.

32. (Cancelled)

33. (Original) The semiconductor package of claim 29, wherein the electrical connection comprises a plurality of metal wires bonded between the semiconductor chip and the inner end segments, wherein at least some of said wires are bonded to the recessed surface of the respective inner end segment.

34. (Cancelled)

35. (Cancelled)

36. (Cancelled)

37. (Currently Amended) The leadframe of claim ~~36~~ **1**, wherein the inner ends of the leads of the ~~first~~ **second** subset extend further toward a center of the leadframe than the inner ends of the leads of the ~~second~~ **first** subset.

38. (Currently Amended) The leadframe of claim 1, wherein the ~~inner end segments of the leads of the first subset include a pedestal between the inner end of the lead and the recess, and the recesses~~ **recess of each of the leads** of the ~~second~~ **first** subset of the leads ~~extend~~ **extends** to the inner end of the lead.

39. (Cancelled)

40. (Currently Amended) The leadframe of claim 9, wherein the inner end of ~~one~~ **the** lead of each said pair **which includes the pedestal** extends further toward a center of the leadframe than the inner end of the other lead of the pair.

41. (Currently Amended) The leadframe of claim 9, wherein ~~one lead of each said pair includes a pedestal between the inner end of the lead and the recessed surface, and~~ the recessed surface of the ~~other~~ lead of the pair **which does not include the pedestal** extends to the inner end of the lead.

42. (Currently Amended) The leadframe of claim 41, wherein the inner end of ~~one~~ **the** lead of each said pair **which includes the pedestal** extends further toward a center of the leadframe than the inner end of the other lead of the pair **which does not include the pedestal**.

43. (Currently Amended) The leadframe of claim 17, wherein the inner end of ~~one~~ **the** lead of each said pair **which includes the pedestal** extends further toward a center of the leadframe than the inner end of the other lead of the pair **which does not include the pedestal**.

44. (Currently Amended) The leadframe of claim 17, wherein ~~one lead of each said pair includes a pedestal between the inner end of the lead and the recessed surface of the lead, and the recessed surface of the other lead, and the recessed surface of the other lead of the pair~~ **which does not include the pedestal** extends to the inner end of the lead.

45. (Currently Amended) The leadframe of claim 44, wherein the inner end of ~~one~~ **the** lead of each said pair **which includes the pedestal** extends further toward a center of the leadframe than the inner end of the other lead of the pair **which does not include the pedestal**.

46. (Currently Amended) The semiconductor package of claim 23, wherein the inner end of ~~one~~ **the** lead of each said pair **which includes the pedestal** extends further toward the semiconductor chip than the inner end of the other lead of the pair **which does not include the pedestal**.

47. (Currently Amended) The semiconductor package of claim 23, wherein ~~one lead of each said pair includes a pedestal between the inner end of the lead and the recessed surface, and the recessed surface of the other lead of the pair~~ **which does not include the pedestal** extends to the inner end of the lead.

48. (Currently Amended) The semiconductor package of claim 47, wherein the inner end of ~~one~~ **the** lead of each said pair **which includes the pedestal** extends further toward ~~a center of the leadframe~~ **the semiconductor chip** than the inner end of the other lead of the pair.

49. (Previously Presented) The semiconductor package of claim 47, wherein the electrical connection to the lead of the pair having the pedestal is located at the pedestal.

50. (Currently Amended) The semiconductor package of claim 29, wherein ~~one lead of each said pair includes a pedestal between the inner end of the lead and the recessed surface~~ **of the lead of the pair which does not include the pedestal extends to the inner end of the lead**.

51. (Currently Amended) The ~~leadframe~~ **semiconductor package** of claim 50, wherein the inner end of ~~one~~ **the** lead of each said pair **which includes the pedestal** extends further toward ~~a center of the leadframe~~ **the semiconductor chip** than the inner end of the other lead of the pair.

52. (Currently Amended) The ~~leadframe~~ **semiconductor package** of claim 29, wherein the inner end of ~~one~~ **the** lead of each said pair **which includes the pedestal** extends further toward ~~a center of the leadframe~~ **the semiconductor chip** than the inner end of the other lead of the pair **which does not include the pedestal**.